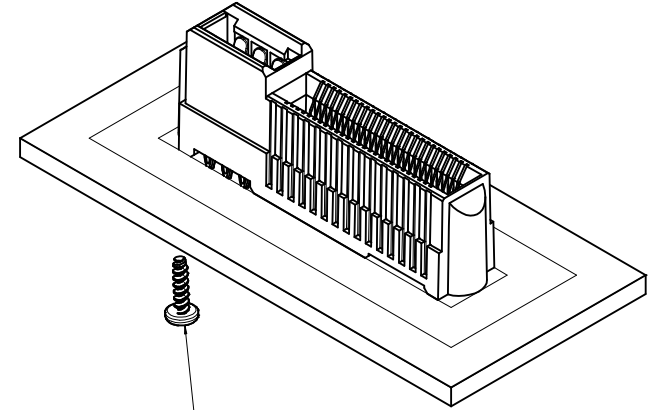
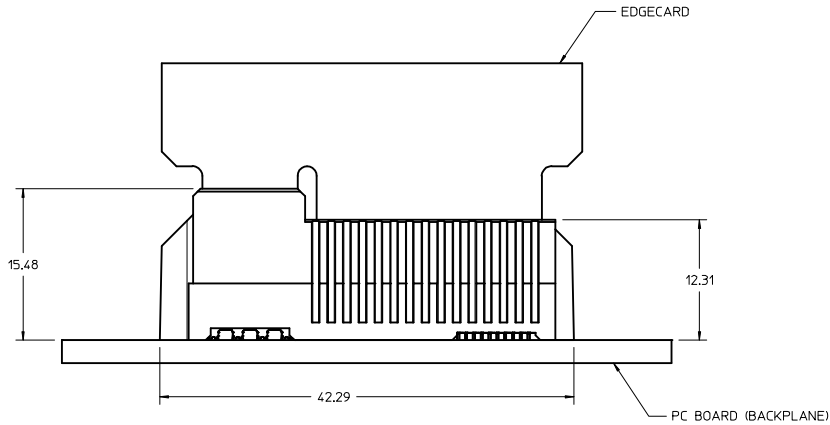
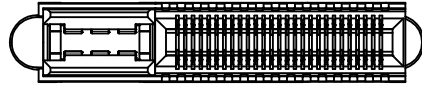
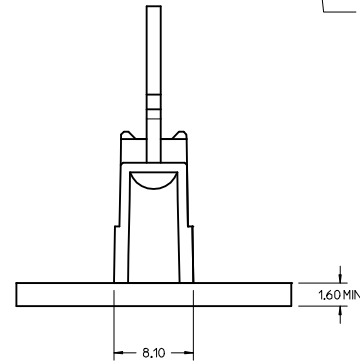


P.C. BOARD MOUNTING



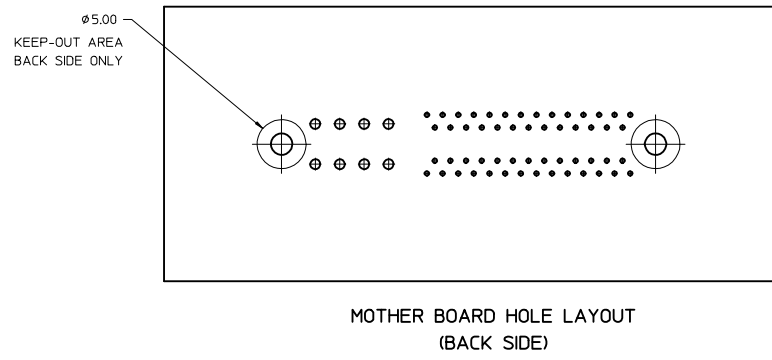
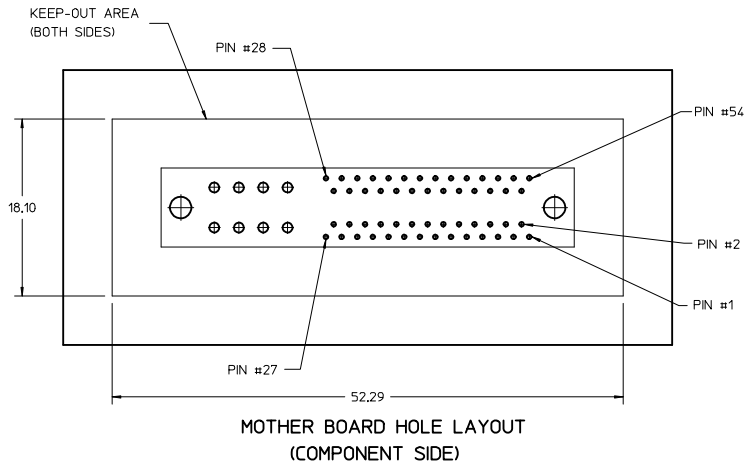
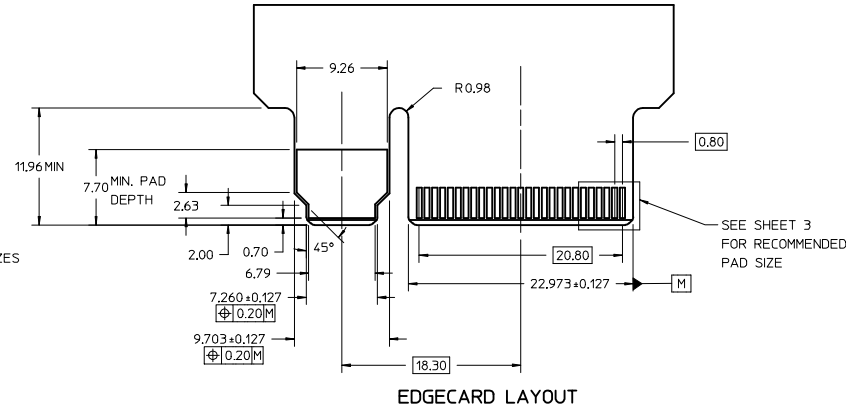
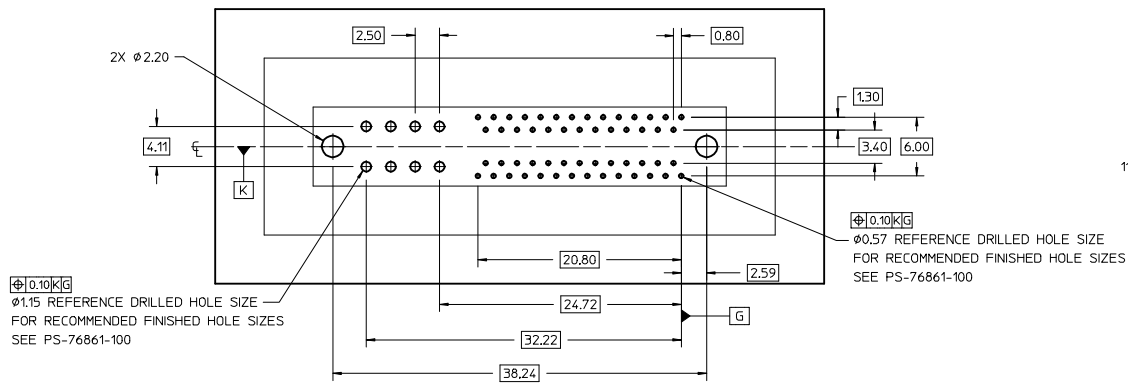
RECOMMENDED THREAD-FORMING SCREW
M1.8x8 (NOT SUPPLIED BY MOLEX)
SEE NOTE 5



NOTES:

1. MATERIAL:
HOUSING - GLASS FILLED THERMOPLASTIC, 94-V0, BLACK
TERMINALS - COPPER ALLOY
2. FINISH:
CONTACT AREA: HARD GOLD -0.76 MICROMETERS MINIMUM OVER 3.80 MICRO METER NICKEL
COMPLIANT AREA: TIN - 0.76/1.52 MICROMETERS OVER NICKEL
3. REFER TO PS-76861-100 PRODUCT SPECIFICATION FOR ALL ELECTRICAL, MECHANICAL AND ENVIRONMENTAL SPECIFICATIONS.
4. REFER TO PK-170545-5000 FOR ALL PACKAGING SPECIFICATIONS.
5. REFER TO AS-76693-100 FOR APPLICATION SPECIFICATIONS.
6. PROCESSING: PRESSFIT TO PC BOARD.
7. MATING PC BOARD THICKNESS = 2.36±10% OVER CONTACT PADS.
8. THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002

TOLERANCE TYPO CORRECTION IEC NO: UICP2017-1945 DRAWN BY: MPOFF 2017/03/09 CHECKED BY: DMORGAN 2017/03/09 APPR: KLANG 2017/03/15 REV DESCRIPTION	QUALITY SYMBOLS		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ±---	mm	INCH	MM ONLY		4:1	METRIC	☉
	▽=0	3 PLACES ±---			DRAWN BY: MPOFF DATE: 2014/05/23				TITLE: EDGELINE ESP30 12.5GB
	▽=0	2 PLACES ±0.13			CHECKED BY: DMORGAN DATE: 2014/05/23				0.093"PCB/0.8MM PITCH
	1 PLACE ±0.25			APPROVED BY: SMILLER DATE: 2014/07/23					54 CKTS
	0 PLACE ±---			ANGULAR ± 2 °					molex
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO:		DOCUMENT NO:		SHEET NO:		
			170545-1054		SD-170545-1054		1 OF 3		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									



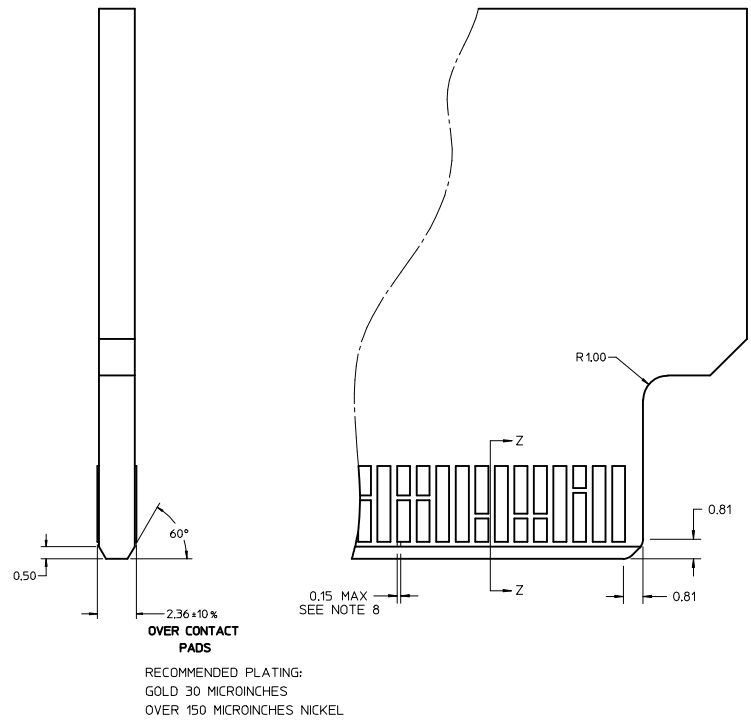
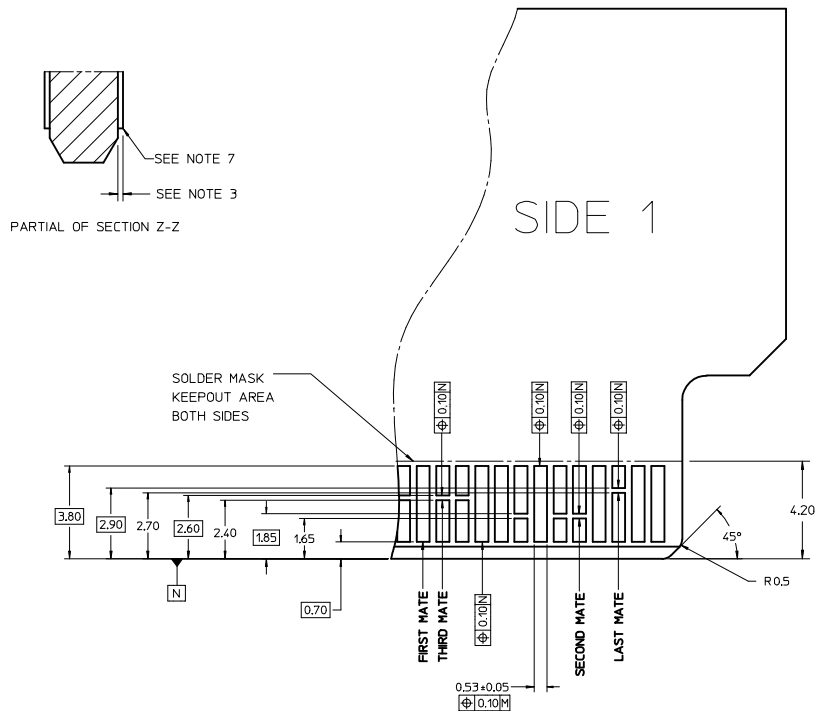
SEE SHEET 1 IEC NO: UCP2017-1945 DRAWN BY: MPOFF 2017/03/09 CHECKED BY: CHYKDMORGAN 2017/03/09 APPROVED BY: APPR:KLANG 2017/03/15 REV DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla=0$	mm INCH	MM ONLY	4:1	METRIC	
	$\nabla=0$	4 PLACES +--- +---	MPOFF 2014/05/23			
	$\nabla=0$	3 PLACES +--- +---	CHECKED BY: DMORGAN 2014/05/23			
	$\nabla=0$	2 PLACES +0.13 +---	APPROVED BY: SMILLER 2014/07/23			
	$\nabla=0$	1 PLACE +0.25 +---				
	$\nabla=0$	0 PLACE +--- +---				
		ANGULAR $\pm 2^\circ$				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				
			MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-170545-1054		
						SHEET NO. 2 OF 3

EDGELINE ESP30 12.5GB
0.093"PCB/0.8MM PITCH
54 CKTS

molex

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

MODULE EDGE CARD CONTACT DETAIL



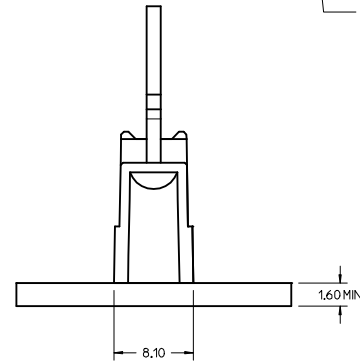
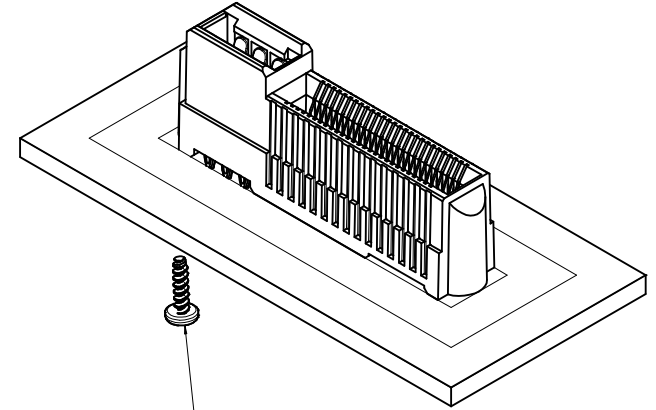
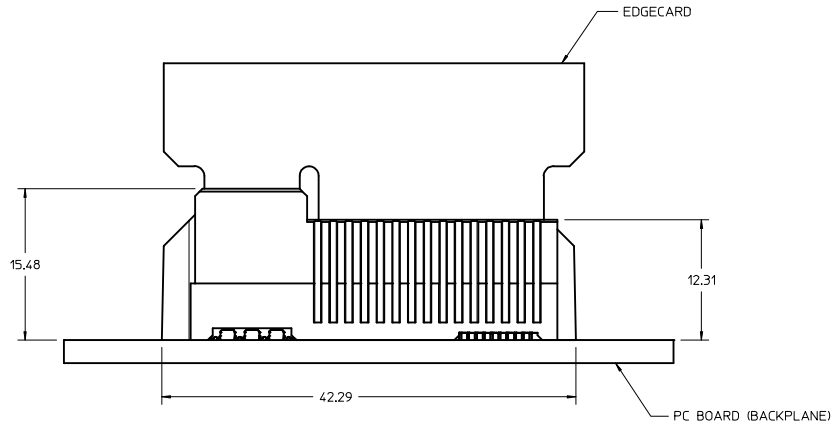
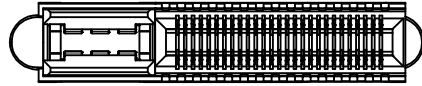
MATING PCB NOTES:

- CONNECTOR LAND CONDITIONS SHALL MEET THE MOST CURRENT REVISION OF PCB SPECIFICATION IPC-6012C-2010 SECTION 3.5.4.4.
- DIMENSIONS APPLY TO LANDS ON BOTH SIDES OF THE BOARD.
- THE THICKNESS OF THE OUTER METAL LAYERS, INCLUDING FOIL, COPPER PLATING, AND THE PROTECTIVE SURFACE FINISH, SHALL BE 0.066mm MAXIMUM.
- CHAMFER ROUGHNESS NOT TO EXCEED 3.17 MICROMETERS.
- CHAMFER PROCESS SHALL NOT DAMAGE THE GOLD EDGE LANDS.
- EDGE CARD CHAMFER NOT TO GO THROUGH GOLD LANDS.
- 0.03mm MAXIMUM PLATING OVERHANG ON ALL GOLD LAND EDGES.
- MOLEX RECOMMENDS NO TIE-BARS ON THE LEADING EDGE OF THE GOLD LAND. IF TIE-BARS ARE USED, THEY SHALL BE PLACED TO ONE SIDE OF THE GOLD LAND. APPLIES TO ALL GOLD LANDS.

SEE SHEET 1 IEC NO: UICP2017-1945 DRAWN BY: CHYKDMORGAN CHECKED BY: APPR:KLANG DATE: 2017/03/09 DATE: 2017/03/15	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES ±0.13 3 PLACES ±0.25 2 PLACES ±0.25 1 PLACE ±0.25 0 PLACE ±0.25	mm INCH	DRAWN BY: MPOFF CHECKED BY: DMORGAN APPROVED BY: SMILLER DATE: 2014/05/23 DATE: 2014/05/23 DATE: 2014/07/23	TITLE EDGELINE ESP30 12.5GB 0.093"PCB/0.8MM PITCH 54 CKTS	MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-170545-1054	SHEET NO. 3 OF 3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

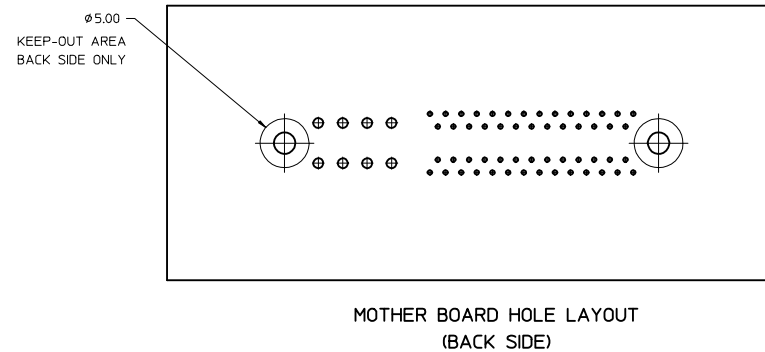
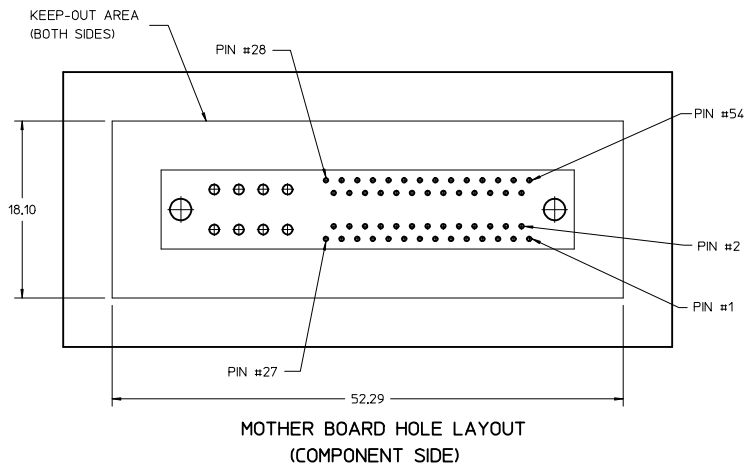
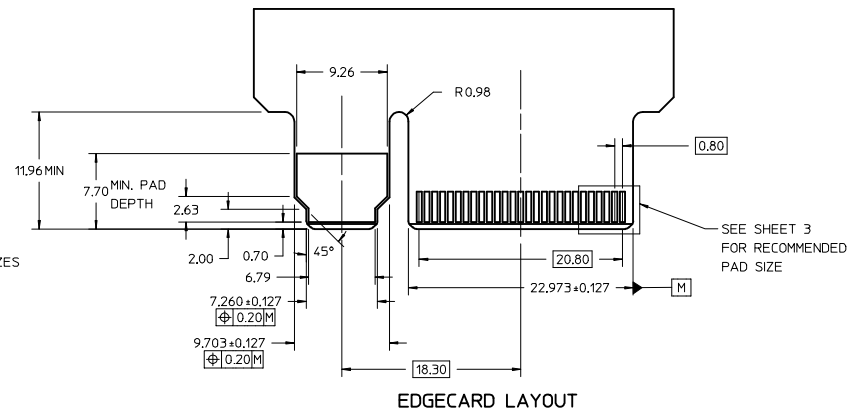
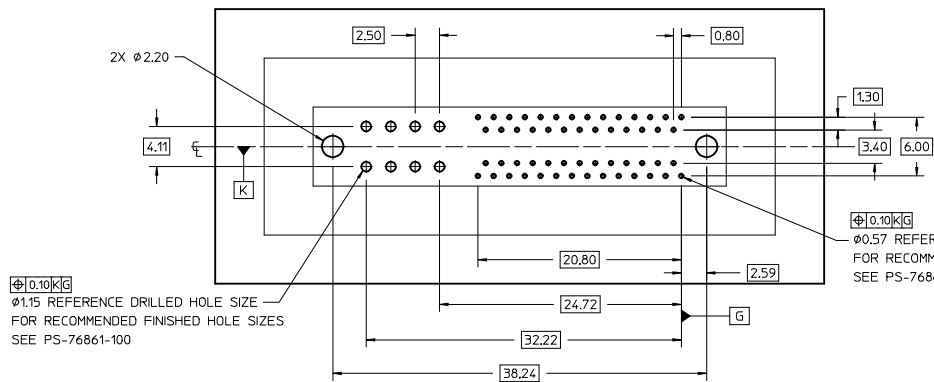
P.C. BOARD MOUNTING



NOTES:

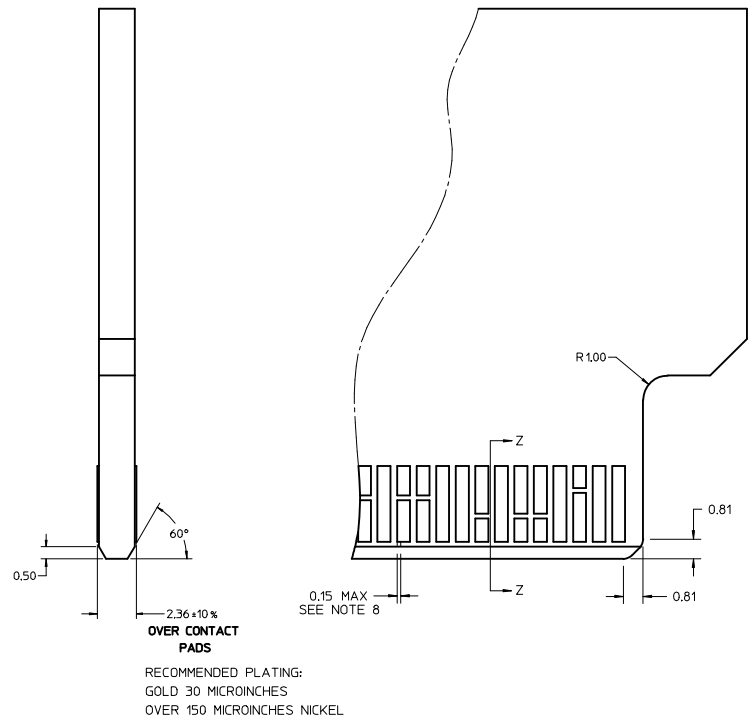
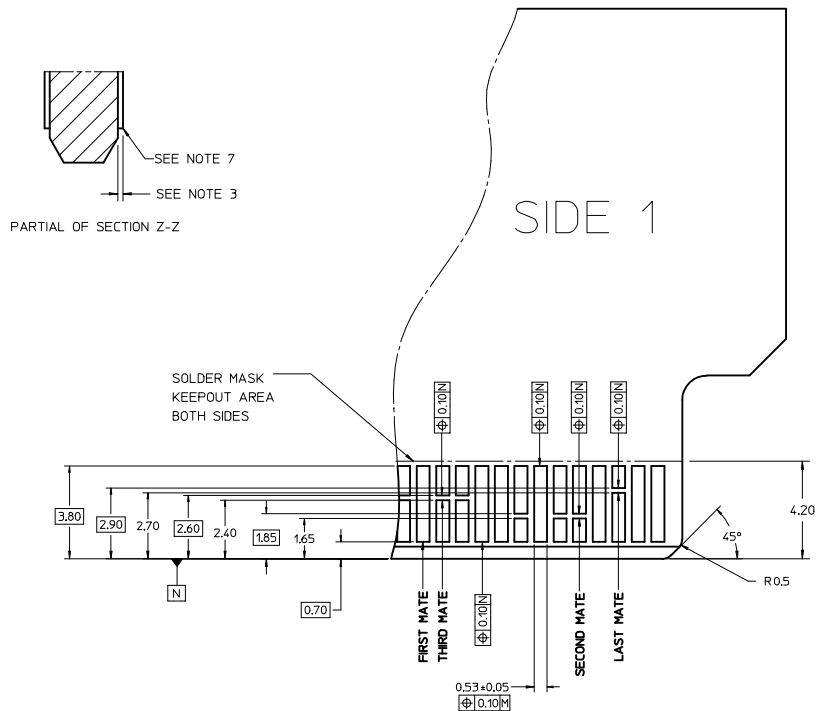
1. MATERIAL:
HOUSING - GLASS FILLED THERMOPLASTIC, 94-V0, BLACK
TERMINALS - COPPER ALLOY
2. FINISH:
CONTACT AREA: HARD GOLD -0.76 MICROMETERS MINIMUM OVER 3.80 MICRO METER NICKEL
COMPLIANT AREA: TIN - 0.76/1.52 MICROMETERS OVER NICKEL
3. REFER TO PS-76861-100 PRODUCT SPECIFICATION FOR ALL ELECTRICAL, MECHANICAL AND ENVIRONMENTAL SPECIFICATIONS.
4. REFER TO PK-170545-5000 FOR ALL PACKAGING SPECIFICATIONS.
5. REFER TO AS-76693-100 FOR APPLICATION SPECIFICATIONS.
6. PROCESSING: PRESSFIT TO PC BOARD.
7. MATING PC BOARD THICKNESS = 2.36±10% OVER CONTACT PADS.
8. THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002

TOLERANCE TYPO CORRECTION IEC NO: UICP2017-1945 DRAWN BY: MPOFF 2017/03/09 CHECKED BY: DMORGAN 2017/03/09 APPR: KLANG 2017/03/15 REV DESCRIPTION	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0		GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1" style="font-size: 8px;"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>±---</td> <td>±---</td> </tr> <tr> <td>3 PLACES</td> <td>±---</td> <td>±---</td> </tr> <tr> <td>2 PLACES</td> <td>±0.13</td> <td>±---</td> </tr> <tr> <td>1 PLACE</td> <td>±0.25</td> <td>±---</td> </tr> <tr> <td>0 PLACE</td> <td>±---</td> <td>±---</td> </tr> </tbody> </table>			mm	INCH	4 PLACES	±---	±---	3 PLACES	±---	±---	2 PLACES	±0.13	±---	1 PLACE	±0.25	±---	0 PLACE	±---	±---	DIMENSION STYLE MM ONLY	SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		mm	INCH																							
	4 PLACES	±---	±---																							
	3 PLACES	±---	±---																							
2 PLACES	±0.13	±---																								
1 PLACE	±0.25	±---																								
0 PLACE	±---	±---																								
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			ANGULAR ± 2 °		DRAWN BY: MPOFF DATE: 2014/05/23 CHECKED BY: DMORGAN DATE: 2014/05/23 APPROVED BY: SMILLER DATE: 2014/07/23	TITLE EDGELINE ESP30 12.5GB 0.093"PCB/0.8MM PITCH 54 CKTS																				
MATERIAL NO: 170545-1054				DOCUMENT NO: SD-170545-1054																						
SIZE D THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							SHEET NO: 1 OF 3																			



SEE SHEET 1 IEC NO: UCP2017-1945 DRAWN BY: MPOFF 2017/03/09 CHECKED BY: CHYKDMORGAN 2017/03/09 APPROVED BY: APPR:KLANG 2017/03/15 REV DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla=0$ $\nabla=0$ $\nabla=0$	4 PLACES \pm --- 3 PLACES \pm --- 2 PLACES \pm 0.13 1 PLACE \pm 0.25 0 PLACE \pm ---	mm INCH ANGULAR \pm 2° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MM ONLY DRAWN BY: MPOFF DATE: 2014/05/23 CHECKED BY: DMORGAN DATE: 2014/05/23 APPROVED BY: SMILLER DATE: 2014/07/23	4:1	METRIC
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						SHEET NO. 2 OF 3

MODULE EDGE CARD CONTACT DETAIL



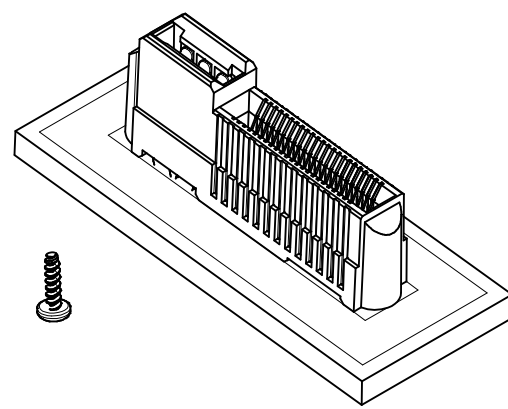
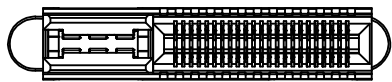
MATING PCB NOTES:

- CONNECTOR LAND CONDITIONS SHALL MEET THE MOST CURRENT REVISION OF PCB SPECIFICATION IPC-6012C-2010 SECTION 3.5.4.4.
- DIMENSIONS APPLY TO LANDS ON BOTH SIDES OF THE BOARD.
- THE THICKNESS OF THE OUTER METAL LAYERS, INCLUDING FOIL, COPPER PLATING, AND THE PROTECTIVE SURFACE FINISH, SHALL BE 0.066mm MAXIMUM.
- CHAMFER ROUGHNESS NOT TO EXCEED 3.17 MICROMETERS.
- CHAMFER PROCESS SHALL NOT DAMAGE THE GOLD EDGE LANDS.
- EDGE CARD CHAMFER NOT TO GO THROUGH GOLD LANDS.
- 0.03mm MAXIMUM PLATING OVERHANG ON ALL GOLD LAND EDGES.
- MOLEX RECOMMENDS NO TIE-BARS ON THE LEADING EDGE OF THE GOLD LAND. IF TIE-BARS ARE USED, THEY SHALL BE PLACED TO ONE SIDE OF THE GOLD LAND. APPLIES TO ALL GOLD LANDS.

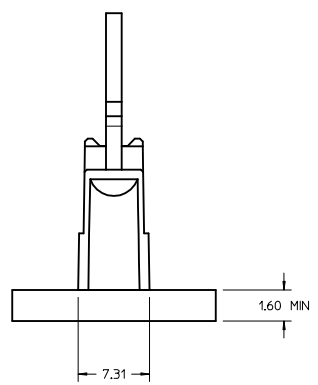
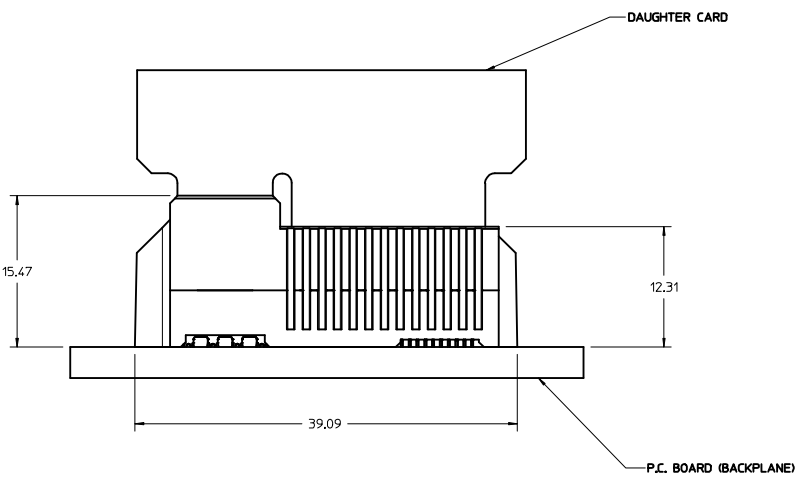
SEE SHEET 1 IEC NO: UICP2017-1945 DRAWN BY: CHYKDMORGAN CHECKED BY: APPR:KLANG DATE: 2017/03/09 DATE: 2017/03/15	QUALITY SYMBOLS ∇=0 ∇=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES ±--- ±--- 3 PLACES ±--- ±--- 2 PLACES ±0.13 ±--- 1 PLACE ±0.25 ±--- 0 PLACE ±--- ±---	mm INCH	DRAWN BY: MPOFF CHECKED BY: DMORGAN APPROVED BY: SMILLER DATE: 2014/05/23 DATE: 2014/05/23 DATE: 2014/07/23	TITLE EDGELINE ESP30 12.5GB 0.093"PCB/0.8MM PITCH 54 CKTS		MATERIAL NO. SEE SHEET 1	DOCUMENT NO. SD-170545-1054

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P.C. BOARD MOUNTING

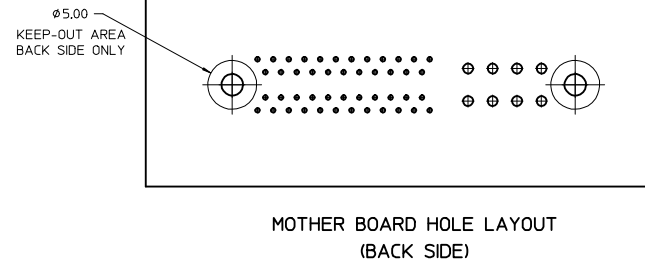
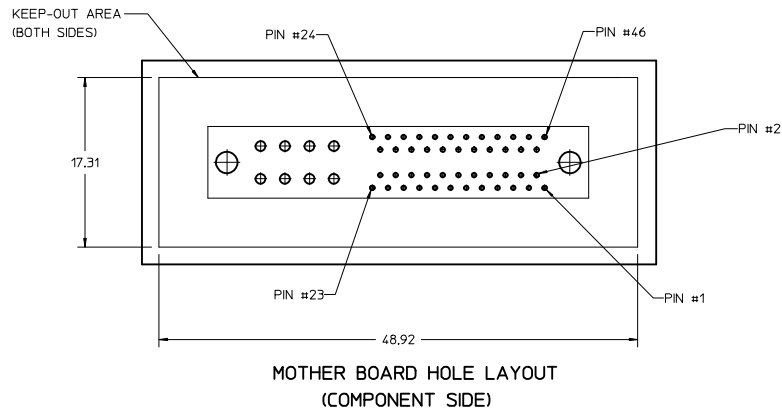
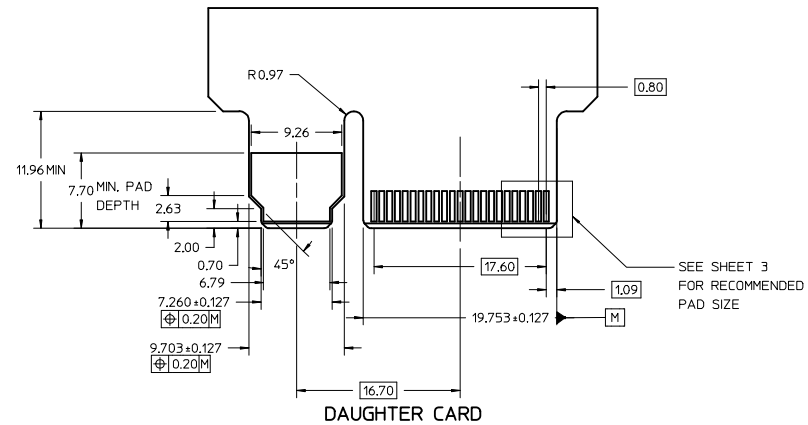
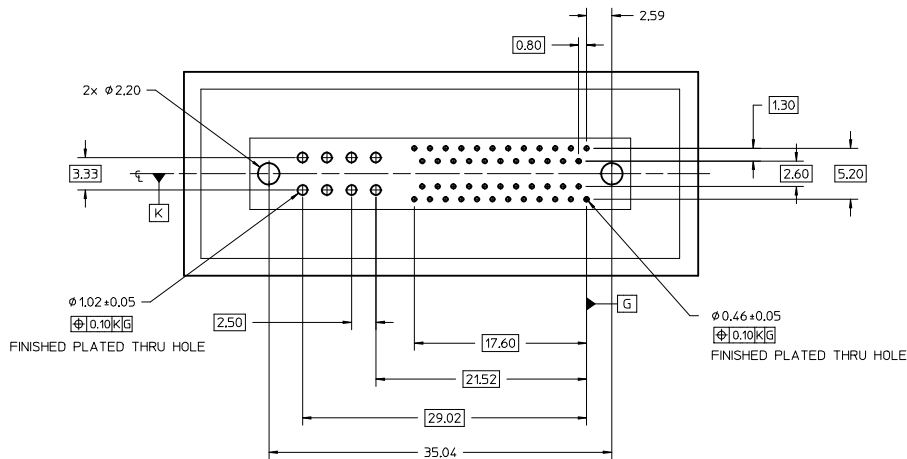


RECOMMENDED THREAD-FORMING SCREW
M1,8x8 (NOT SUPPLIED BY MOLEX)
SEE NOTE 8



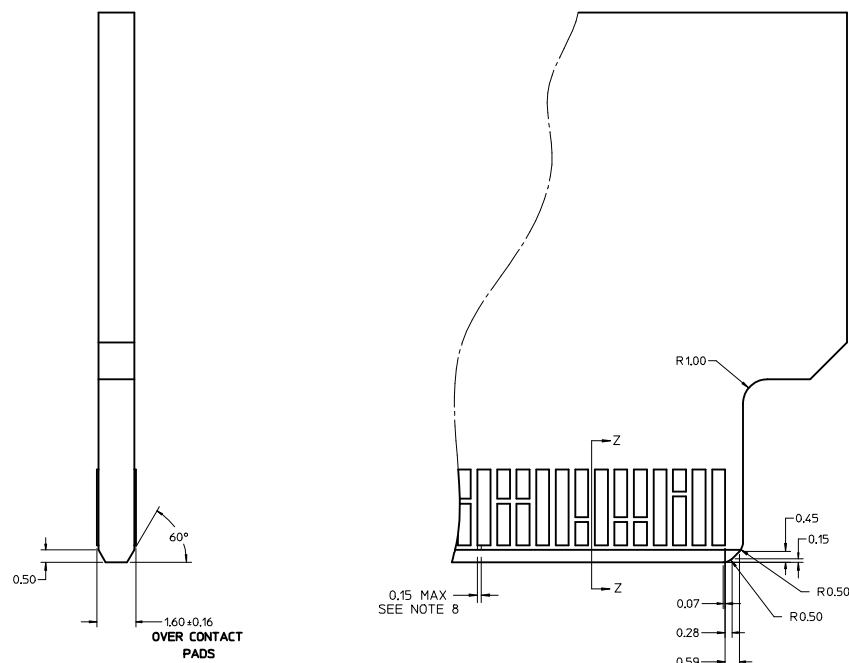
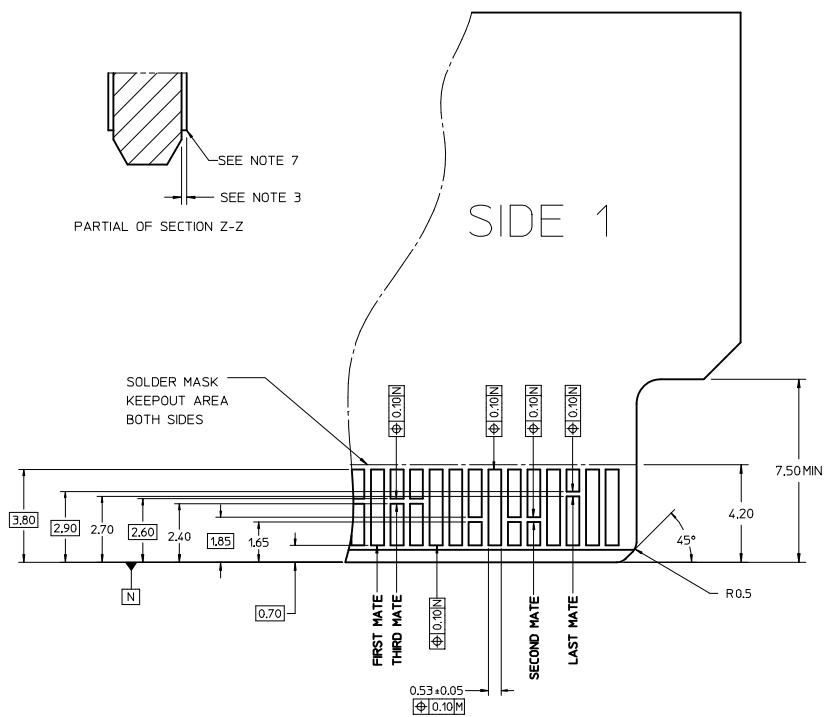
- NOTES:
- MATERIAL:
HOUSING - GLASS FILLED THERMOPLASTIC, 94-V0, BLACK
TERMINALS - COPPER ALLOY
 - FINISH:
CONTACT AREA: HARD GOLD -0.76µm MIN OVER 3.80µ NICKEL
COMPLIANT AREA: TIN - 0.76/152µm OVER NICKEL
 - REFER TO PS-76861-100 PRODUCT SPECIFICATION FOR ALL ELECTRICAL, MECHANICAL AND ENVIRONMENTAL SPECIFICATIONS.
 - REFER TO PK-76861-900 FOR ALL PACKAGING SPECIFICATIONS.
 - PROCESSING: PRESSFIT TO PC BOARD.
 - MATING PC BOARD THICKNESS = 1.60±0.16MM OVER CONTACT PADS.
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002.
 - REFER TO APPLICATION SPECIFICATION AS-76693-100 FOR MORE DETAILS

DAUGHTER CARD PS-76861-100 EC NO: UICP 2017-1680 DRAWN BY: DRWN:HPDFF 2017/02/17 CHECKED BY: CHKD:DMORGAN 2017/02/17 APPR:KLANG 2017/02/27 REV DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ± 0.13 ± 0.05	MM ONLY	4:1	METRIC	☉
	▽=0	3 PLACES ± 0.13 ± 0.05				
	▽=0	2 PLACES ± 0.25 ± 0.10				
		ANGULAR ± 2 °	DRAWN BY: DROSCA DATE: 12/02/2008			TITLE: EDGELINE+LPH 12.5GB 0.062"PCB/0.8MM PITCH 46 CKTS
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	CHECKED BY: JCOMERC I DATE: 12/02/2008			molex MATERIAL NO. 76861-1000 DOCUMENT NO. SD-76861-100 SHEET NO. 1 OF 3
			APPROVED BY: JCOMERC I DATE: 2009/08/04			



SEE SHEET 1 EC NO: UCP2017-1680 DRAWN BY: CHYKOSMORGAN CHECKED BY: APPR:KLANG DATE: 2017/02/17 DATE: 2017/02/27 DESCRIPTION:	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	4 PLACES ± mm ± INCH	MM ONLY	4:1	METRIC	EDGELINE+LPH 12.5GB
	▽=0	3 PLACES ± mm ± INCH				0.062"PCB/0.8MM PITCH
	▽=0	2 PLACES ± 0.13 ± INCH				46 CKTS
		1 PLACE ± 0.25 ± INCH				molex
		0 PLACE ± mm ± INCH				MATERIAL NO. DOCUMENT NO.
		ANGULAR ± 2 °				SEE SHEET 1 SD-76861-100
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SHEET NO. 2 OF 3
						THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

MODULE EDGE CARD CONTACT DETAIL



RECOMMENDED PLATING:
GOLD 30μM INCHES
OVER 150μM INCHES
NICKEL

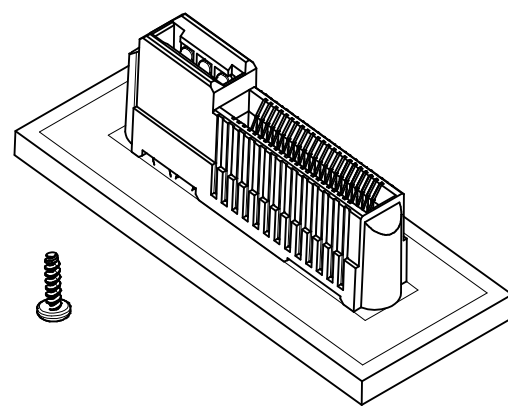
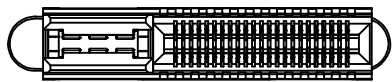
MATING PCB NOTES:

- CONNECTOR LAND CONDITIONS SHALL MEET THE MOST CURRENT REVISION OF PCB SPECIFICATION IPC-6012C-2010 SECTION 3.5.4.4.
- DIMENSIONS APPLY TO LANDS ON BOTH SIDES OF THE BOARD.
- THE THICKNESS OF THE OUTER METAL LAYERS, INCLUDING FOIL, COPPER PLATING, AND THE PROTECTIVE SURFACE FINISH, SHALL BE 0.066mm MAX.
- CHAMFER ROUGHNESS NOT TO EXCEED 3.17 MICROMETERS.
- CHAMFER PROCESS SHALL NOT DAMAGE THE GOLD EDGE LANDS.
- EDGE CARD CHAMFER NOT TO GO THRU GOLD LANDS.
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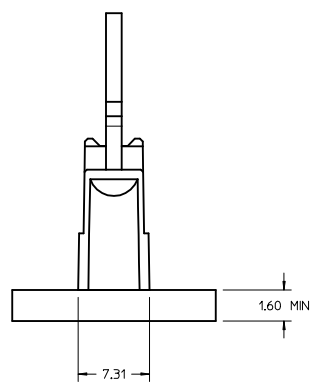
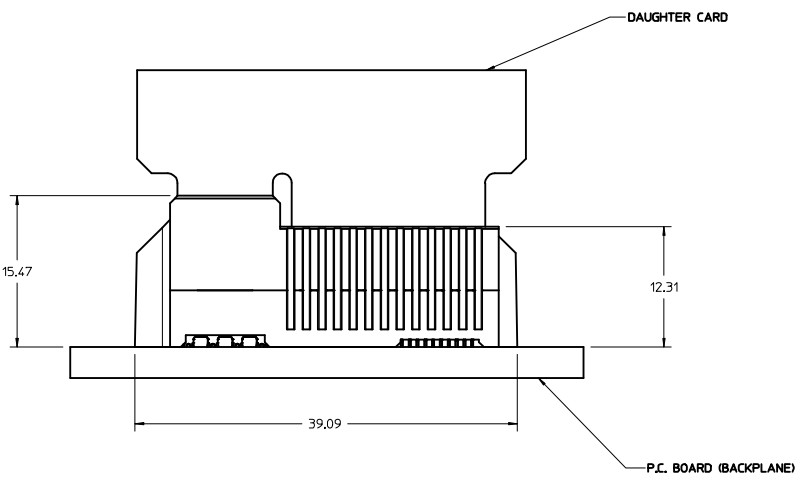
SEE SHEET 1 EC NO: UCP2017-1680 DRAWN BY: DRWINHPOFF CHECKED BY: CHYKDMORGAN APPROVED BY: APPR:KLANG DATE: 2017/02/17 DATE: 2017/02/17 DATE: 2017/02/27	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES ± --- INCH 3 PLACES ± --- INCH 2 PLACES ± 0.13 INCH 1 PLACE ± 0.25 INCH 0 PLACE ± --- INCH	4 PLACES ± --- MM 3 PLACES ± --- MM 2 PLACES ± 0.13 MM 1 PLACE ± 0.25 MM 0 PLACE ± --- MM	DRAWN BY: DROSCA DATE: 12/02/2008 CHECKED BY: JCOMERC I DATE: 12/02/2008 APPROVED BY: JCOMERC I DATE: 2009/08/04	TITLE EDGELINE+LPH 12.5GB 0.062"PCB/0.8MM PITCH 46 CKTS	MATERIAL NO. SD-76861-100	DOCUMENT NO.	SHEET NO. 3 OF 3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

P.C. BOARD MOUNTING

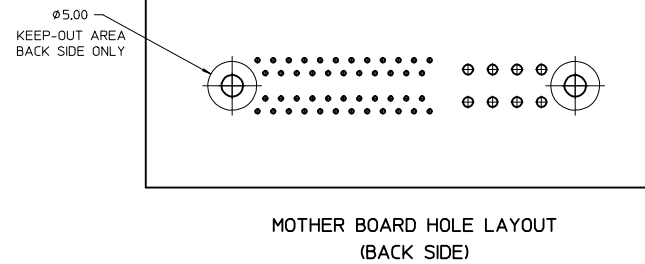
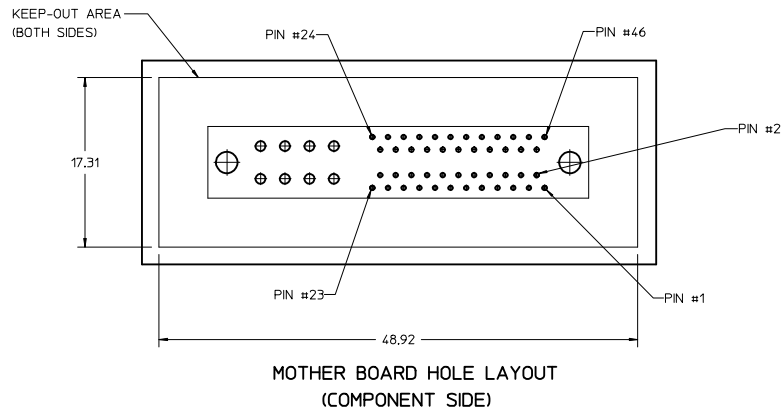
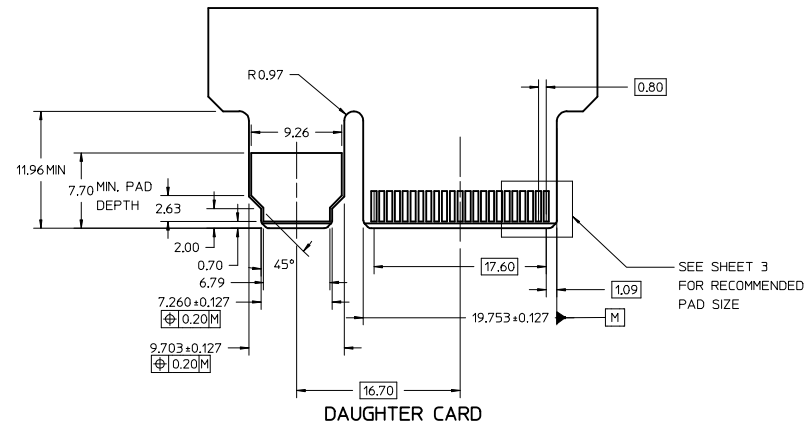
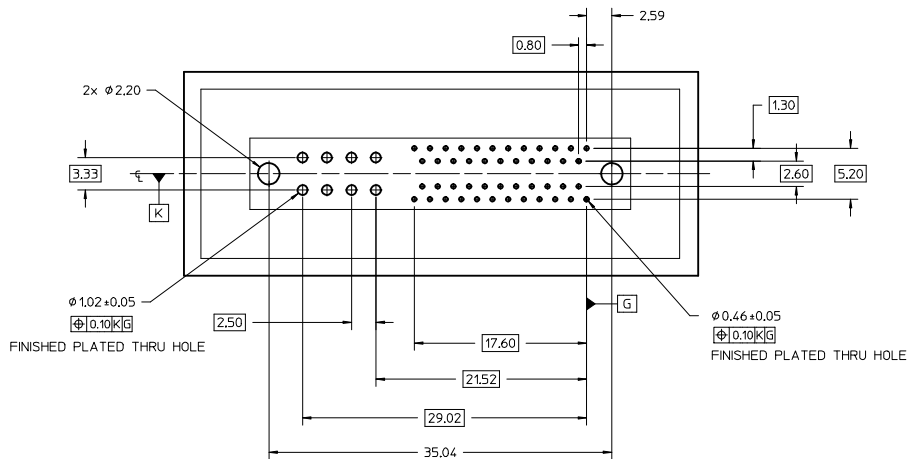


RECOMMENDED THREAD-FORMING SCREW
M1,8x8 (NOT SUPPLIED BY MOLEX)
SEE NOTE 8



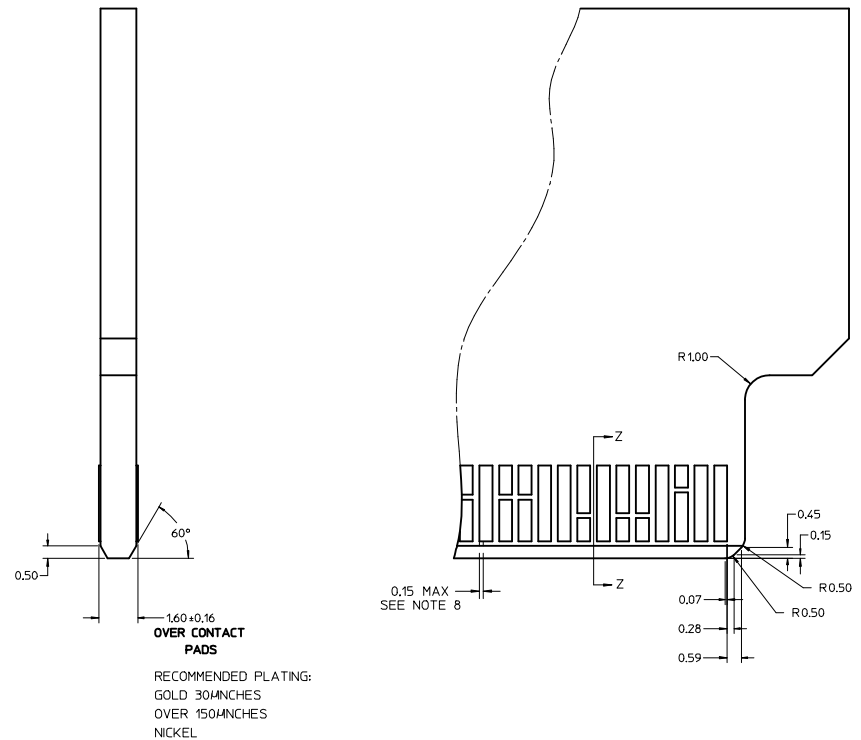
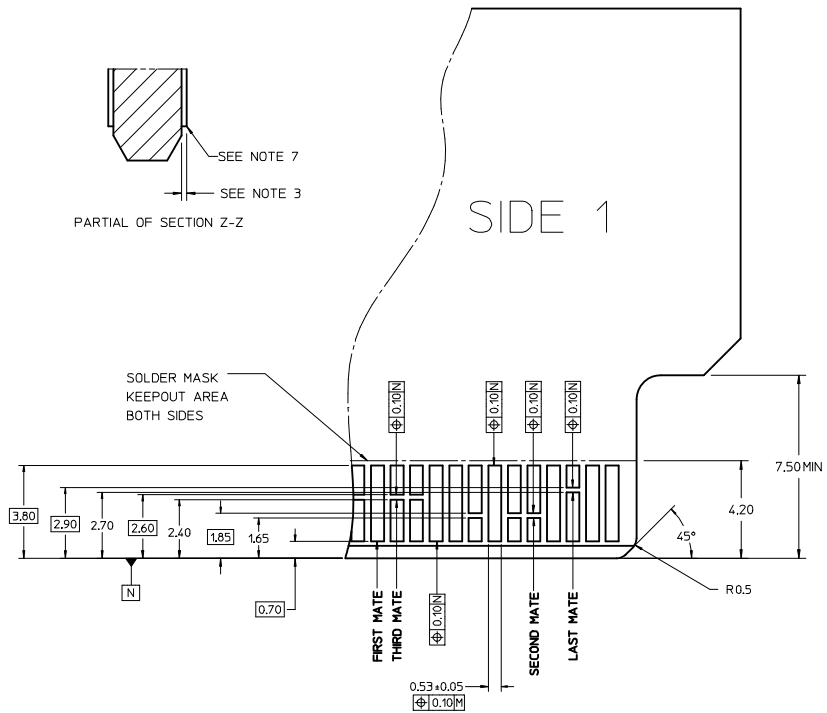
- NOTES:
- MATERIAL:
HOUSING - GLASS FILLED THERMOPLASTIC, 94-V0, BLACK
TERMINALS - COPPER ALLOY
 - FINISH:
CONTACT AREA: HARD GOLD -0.76µm MIN OVER 3.80µ NICKEL
COMPLIANT AREA: TIN - 0.76/152µm OVER NICKEL
 - REFER TO PS-76861-100 PRODUCT SPECIFICATION FOR ALL ELECTRICAL, MECHANICAL AND ENVIRONMENTAL SPECIFICATIONS.
 - REFER TO PK-76861-900 FOR ALL PACKAGING SPECIFICATIONS.
 - PROCESSING: PRESSFIT TO PC BOARD.
 - MATING PC BOARD THICKNESS = 1.60±0.16MM OVER CONTACT PADS.
 - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002.
 - REFER TO APPLICATION SPECIFICATION AS-76693-100 FOR MORE DETAILS

DAUGHTER CARD PS-76861-100 EC NO: UICP 2017-1680 DRAWN BY: DRWINHOFF 2017/02/17 CHECKED BY: CHYKSDMORGAN 2017/02/17 APPR: KLING 2017/02/27 REV DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▽=0	4 PLACES ± --- ± ---	MM ONLY	4:1	METRIC	☉	
	▽=0	3 PLACES ± --- ± ---					
	▽=0	2 PLACES ± 0.13 ± ---					
		1 PLACE ± 0.25 ± ---					
		0 PLACE ± --- ± ---					
		ANGULAR ± 2 °					
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					
			MATERIAL NO.	DOCUMENT NO.			
			76861-1000	SD-76861-100			
			DRAWN BY: DROSCA 12/02/2008		TITLE: EDGELINE+LPH 12.5GB		
			CHECKED BY: JCOMERC I 12/02/2008		0.062"PCB/0.8MM PITCH		
			APPROVED BY: JCOMERC I 2009/08/04		46 CKTS		
			DATE: 2009/08/04		molex		
						SHEET NO. 1 OF 3	
			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



SEE SHEET 1 EC NO: UCP2017-1680 DRAWN BY: CHYKOSMORGAN CHECKED BY: APPR:KLANG DATE: 2017/02/17 DATE: 2017/02/27 DESCRIPTION:	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	$\nabla=0$ $\nabla=0$ $\nabla=0$	4 PLACES ± mm ± INCH 3 PLACES ± mm ± INCH 2 PLACES ± 0.13 ± mm ± INCH 1 PLACE ± 0.25 ± mm ± INCH 0 PLACE ± mm ± INCH	MM ONLY	4:1	METRIC	EDGELINE+LPH 12.5GB 0.062"PCB/0.8MM PITCH 46 CKTS
DRAWN BY: CHYKOSMORGAN CHECKED BY: APPR:KLANG DATE: 2017/02/17 DATE: 2017/02/27	DRAWN BY: DROSCA CHECKED BY: JCOMERC I APPROVED BY: JCOMERC I DATE: 12/02/2008 DATE: 12/02/2008 DATE: 2009/08/04	MATERIAL NO. DOCUMENT NO.	SEE SHEET 1	SD-76861-100	SHEET NO. 2 OF 3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

MODULE EDGE CARD CONTACT DETAIL



MATING PCB NOTES:

- CONNECTOR LAND CONDITIONS SHALL MEET THE MOST CURRENT REVISION OF PCB SPECIFICATION IPC-6012C-2010 SECTION 3.5.4.4.
- DIMENSIONS APPLY TO LANDS ON BOTH SIDES OF THE BOARD.
- THE THICKNESS OF THE OUTER METAL LAYERS, INCLUDING FOIL, COPPER PLATING, AND THE PROTECTIVE SURFACE FINISH, SHALL BE 0.066mm MAX.
- CHAMFER ROUGHNESS NOT TO EXCEED 3.17 MICROMETERS.
- CHAMFER PROCESS SHALL NOT DAMAGE THE GOLD EDGE LANDS.
- EDGE CARD CHAMFER NOT TO GO THRU GOLD LANDS.
- 0.03mm MAX PLATING OVERHANG ON ALL GOLD LAND EDGES.
- MOLEX RECOMMENDS NO TIE-BARS ON THE LEADING EDGE OF THE GOLD LAND. IF TIE-BARS ARE USED, THEY SHALL BE PLACED TO ONE SIDE OF THE GOLD LAND, APPLIES TO ALL GOLD LANDS.

SEE SHEET 1 EC NO: UCP2017-1680 DRAWN BY: DRW/HP/POFF CHECKED BY: CHK/D/MORGAN APPROVED BY: APPR/K/LANG DATE: 2017/02/17 DATE: 2017/02/17 DATE: 2017/02/27	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED) <table border="1"> <thead> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> </thead> <tbody> <tr> <td>4 PLACES</td> <td>±---</td> <td>±---</td> </tr> <tr> <td>3 PLACES</td> <td>±---</td> <td>±---</td> </tr> <tr> <td>2 PLACES</td> <td>±0.13</td> <td>±---</td> </tr> <tr> <td>1 PLACE</td> <td>±0.25</td> <td>±---</td> </tr> <tr> <td>0 PLACE</td> <td>±---</td> <td>±---</td> </tr> </tbody> </table> ANGULAR ± 2 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		mm	INCH	4 PLACES	±---	±---	3 PLACES	±---	±---	2 PLACES	±0.13	±---	1 PLACE	±0.25	±---	0 PLACE	±---	±---	DIMENSION STYLE MM ONLY DRAWN BY: DROSCA CHECKED BY: JCOMERC I APPROVED BY: JCOMERC I DATE: 12/02/2008 DATE: 12/02/2008 DATE: 2009/08/04	SCALE: 10:1 DESIGN UNITS: METRIC THIRD ANGLE PROJECTION	TITLE: EDGELINE+LPH 12.5GB 0.062"PCB/0.8MM PITCH 46 CKTS molex	MATERIAL NO.: DOCUMENT NO.: SD-76861-100 SHEET NO.: 3 OF 3
		mm	INCH																					
4 PLACES	±---	±---																						
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